

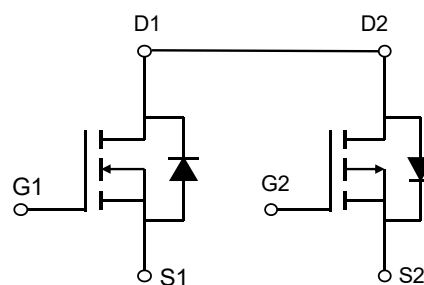
Description

Features

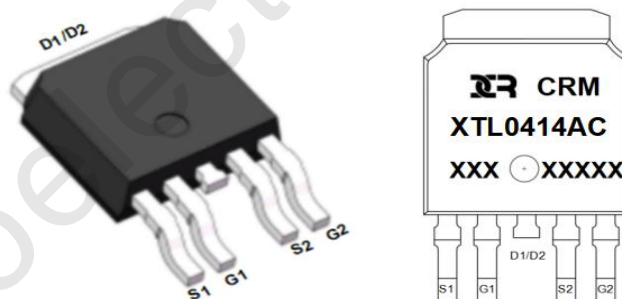
- 40V, 25A
 $R_{DS(ON)}$ Typ = 15.4m Ω @ V_{GS} = 10V
 $R_{DS(ON)}$ Typ = 21m Ω @ V_{GS} = 4.5V
- -40V, -18A
 $R_{DS(ON)}$ Typ = 28m Ω @ V_{GS} = -10V
 $R_{DS(ON)}$ Typ = 39.5m Ω @ V_{GS} = -4.5V
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead Free
- 100% UIS TESTED!
- 100% ΔV_{ds} TESTED!

Application

- Load Switch
- PWM Application
- Power Management



Schematic Diagram



Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMXTL0414AC	CRMXTL0414AC	TO-252-4L	TAPING	13"	2500	25000

Absolute Maximum Ratings (@ T_J = 25°C unless otherwise specified)

Symbol	Parameter	N Value	P Value	Units
V_{DS}	Drain-to-Source Voltage	40	-40	V
V_{GS}	Gate-to-Source Voltage	± 20	± 20	V
I_D	Continuous Drain Current	$T_C = 25^\circ\text{C}$	25	A
		$T_C = 100^\circ\text{C}$	4.5	A
I_{DM}	Pulsed Drain Current ⁽¹⁾	100	-72	A
E_{AS}	Single Pulsed Avalanche Energy ⁽²⁾	30	30	mJ
P_D	Power Dissipation	$T_C = 25^\circ\text{C}$	20.7	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case	6	6	°C/W
T_J, T_{STG}	Junction & Storage Temperature Range	-55 to 150		°C

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	I _D = 250μA, V _{GS} = 0V	40	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 40V, V _{GS} = 0V	-	-	1.0	μA
I _{GSS}	Gate-Body Leakage Current	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	1	1.5	2	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽³⁾	V _{GS} = 10V, I _D = 10A	-	15.4	20	mΩ
		V _{GS} = 4.5V, I _D = 7A	-	21	27.3	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{GS} = 0V, V _{DS} = 20V, f = 1MHz	-	1000	-	pF
C _{oss}	Output Capacitance		-	84	-	pF
C _{rss}	Reverse Transfer Capacitance		-	63	-	pF
Q _g	Total Gate Charge	V _{GS} = 0 to 10V V _{DS} = 20V, I _D = 5A	-	14	-	nC
Q _{gs}	Gate Source Charge		-	4	-	nC
Q _{gd}	Gate Drain("Miller") Charge		-	4.5	-	nC
Switching Characteristics						
t _{d(on)}	Turn-On DelayTime	V _{GS} = 10V, V _{DD} = 20V I _D = 5A, R _{GEN} = 3Ω	-	10	-	ns
t _r	Turn-On Rise Time		-	12	-	ns
t _{d(off)}	Turn-Off DelayTime		-	33	-	ns
t _f	Turn-Off Fall Time		-	10	-	ns
Drain-Source Diode Characteristics and Max Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	25	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	100	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S = 10A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	I _F = 5A, di/dt = 100A/us	-	19	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	11	-	nC

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	I _D = -250μA, V _{GS} = 0V	-40	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -40V, V _{GS} = 0V	-	-	-1.0	μA
I _{GSS}	Gate-Body Leakage Current	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = -250μA	-1.1	-1.6	-2.2	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽³⁾	V _{GS} = -10V, I _D = -8A	-	28	36.4	mΩ
		V _{GS} = -4.5V, I _D = -6A	-	39.5	51.4	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{GS} = 0V, V _{DS} = -20V, f = 1MHz	-	887	-	pF
C _{oss}	Output Capacitance		-	92	-	pF
C _{rss}	Reverse Transfer Capacitance		-	79	-	pF
Q _g	Total Gate Charge	V _{GS} = 0 to -10V V _{DS} = -20V, I _D = -3A	-	35	-	nC
Q _{gs}	Gate Source Charge		-	6	-	nC
Q _{gd}	Gate Drain("Miller") Charge		-	7	-	nC
Switching Characteristics						
t _{d(on)}	Turn-On DelayTime	V _{GS} = -10V, V _{DD} = -20V I _D = -5A, R _{GEN} = 3Ω	-	13	-	ns
t _r	Turn-On Rise Time		-	10	-	ns
t _{d(off)}	Turn-Off DelayTime		-	20	-	ns
t _f	Turn-Off Fall Time		-	12	-	ns
Drain-Source Diode Characteristics and Max Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	-18	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-72	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S = -8A	-	-	-1.2	V
trr	Body Diode Reverse Recovery Time	I _F = -3A, di/dt = 100A/us	-	23	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	15	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
 2. E_{AS} condition: Starting $T_J = 25^\circ\text{C}$, $V_{DD} = 20\text{V}$, $V_G = 10\text{V}$, $R_G = 25\text{ohm}$, $L = 0.5\text{mH}$, $I_{AS} = 11\text{A}$
 E_{AS} condition: Starting $T_J = 25^\circ\text{C}$, $V_{DD} = -20\text{V}$, $V_G = -10\text{V}$, $R_G = 25\text{ohm}$, $L = 0.5\text{mH}$, $I_{AS} = -11\text{A}$
 3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$.

Test Circuit

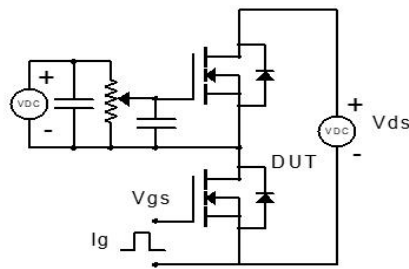


Figure 1: Gate Charge Test Circuit & Waveform

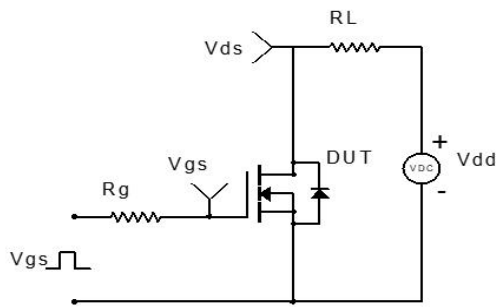


Figure 2: Resistive Switching Test Circuit & Waveform

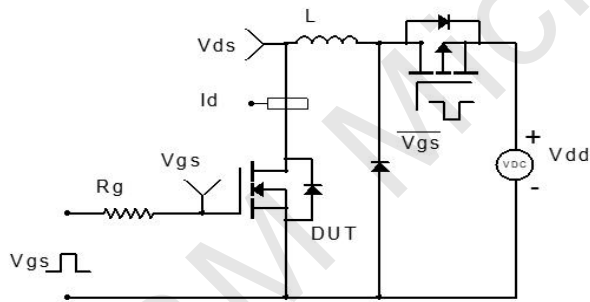


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

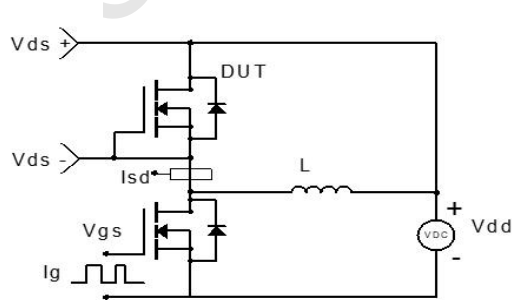
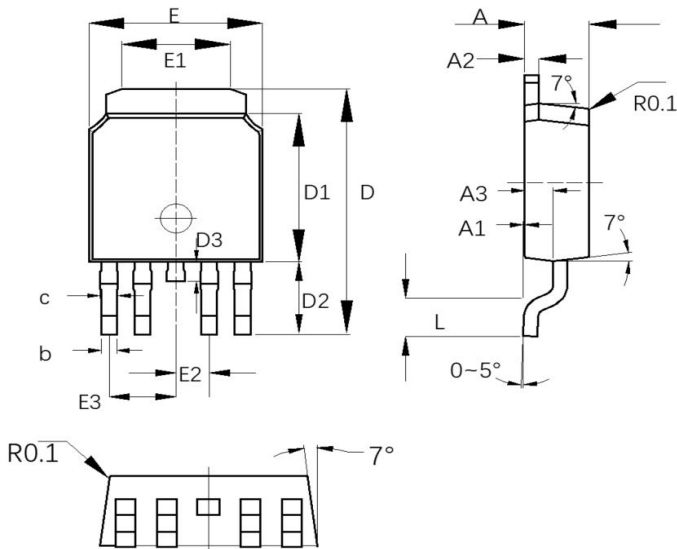


Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(TO-252-4L)




COMMON DIMENSION (MM)			
PKG	TO-252-4L		
Symbol	MIN	MON	MAX
A	2.250	2.300	2.400
A1	0.010	0.060	0.150
A2	0.500	0.508	0.550
A3	0.960	1.010	1.060
b	0.570	0.600	0.630
c	-	-	0.900
D	9.800	10.025	10.35
D1	6.050	6.100	6.180
D2	2.850	2.900	2.950
D3	0.700	0.800	0.900
E	6.550	6.600	6.700
E1	4.050	4.130	4.200
E2	1.240	1.270	1.300
E3	2.510	2.540	2.570
L	1.400	1.500	1.600

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